



## **PRODUCT DATASHEET**



- ▶ PTH/THT Lamp
- 3mm Round 5.3t
  - Photodiode (PD)

# NOP60L55 (Bulk) NOP60L55T (Tape)





## **FEATURES:**

NOP60L55 is silicon planar PIN photodiodes incorporated in THT/PTH packages that simultaneously serve as filters, and also transparent for infrared emission. The PIN photodiodes are outstanding for low junction capacitance, high cut-off frequency and fast switching times.

- Package: PTH/THT LED Lamp 3mm Round 5.3t .
- Wavelength of Max. Sensitivity (typ.): 950nm •
- **Receiving Angle: 30°** •
- Materials: .
  - **Die: Silicon Planar** \_
  - Resin: Epoxy (Black Clear)
  - Operating Temperature: -40~+85°C
  - Storage Temperature: -50~+100°C
- Soldering methods: Hand; Soldering Heat (DIP)
- MSL Level: acc. to JEDEC Level 3 .
- Packing: 500pcs/bulk; 2000pcs/tape (Ammo Pack)

3mm Round Lamp

## **APPLICATIONS:**

- **Remote Control**
- Automatic Control System
- **Burglar Alarm** •
- Photo Detector •
- Smoke

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- Detector
- Computer I/O Peripheral
- Industrial Use



## CHARACTERISTICS:

### Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Power Dissipation	PD	100	mW
Operating Temperature	Topr	-40~+85	°C
Storage Temperature	Тѕтб	-50~+100	°C
Relative Humidity at 85°C	hr	85	%

#### Electrical & Optical Characteristics (Ta=25°C)

Deremeter	Symbol	Values			11	Test Candition
Parameter		Min.	Тур.	Max.	Unit	lest Condition
Reverse Light Current	١L	13	20		μΑ	$V_R$ =5V E <sub>e</sub> =1mW/cm <sup>2</sup> $\lambda_p$ =940nm
Wavelength of Peak Sensitivity	$\lambda_{p(MAX)}$	700	950		nm	
Reverse Breakdown Voltage	V(BR)R	33	170		v	lr=100μA E <sub>e</sub> =0mW/cm <sup>2</sup>
Open Circuit Voltage	Voc		165		mV	$E_e=0.5mW/cm^2$ $\lambda_p=940nm$
			110		mV	$E_e$ =0.05mW/cm <sup>2</sup> $\lambda_p$ =940nm
Short Circuit Current	lsc		1.5		μA	$E_e=0.1mW/cm^2$ $\lambda_p=940nm$
Turn-On Time	Ton		50		nS	RL=1K V <sub>R</sub> =10V
Turn-Off Time	$T_{off}$		50		nS	RL=1K V <sub>R</sub> =10V
Temperature Coefficient of Vo	Tc		-2.6		mV/K	
Radiant Sensitive Area	А		7.7		mm²	
Dark Current	I <sub>D(R)</sub>		2	30	nA	V <sub>R</sub> =10V E <sub>e</sub> =0mW/cm <sup>2</sup>
Total Capacitance	Ct		25	30	PF	V <sub>R</sub> =3V F=1MHz E <sub>e</sub> =0mW/cm <sup>2</sup>

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## **OUTLINE DIMENSION:**

#### Package Dimension:



1. All dimensions are in millimetre (mm).

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2. Tolerance ±0.2mm, unless otherwise noted.



## **ELECTRO-OPTICAL CHARACTERISTICS:**









## **RECOMMENDED SOLDERING PROFILE:**

Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds ± 1 sec.

#### Soldering Heat (DIP):



Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



## **PACKING SPECIFICATION:**

#### Reel Dimension:



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## **PRECAUTIONS OF USE:**



#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

#### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

#### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

#### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



## **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	16/04/2023	Datasheet set-up.